03-22-2002

102027961

Docket No. FSI0006/US/2

To: The Honorable Commissioner of Patents and Trademarks
Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)/(Execution Date)

Devendra Kumar	February 5, 2002
Jeffrey D. Womack	January 27, 2002
Vuong P. Nguyen	January 27, 2002
Jack S. Kasahara	January 25, 2002
Sokol Ibrani	January 28, 2002

3-8-02

Additional names of conveying party(ies) attached?
☐ Yes ☒ No

Name and address of receiving party(ies):

FSI International, Inc.
3455 Lyman Boulevard
Chaska, Minnesota 55318-1096

Additional names of receiving party(ies) attached?
☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other
☐ If this is a request for correction of a previously recorded document, a copy of the previously recorded assignment and previous Notice of Recordation is enclosed.

4. Application number or patent number:

☐ This document is being filed with a new patent application on: _____
☒ This document is to be recorded against the following patent application or patent: 09/903,114
☐ **Patent Cooperation Treaty (PCT):**
Enter PCT application number only if a U.S. Application Number has not been assigned: _____

Additional Numbers Attached? ☐ Yes ☒ No

OFFICE OF PUBLIC RECORDS
2002 MAR -8 AM 11:44
FINANCE SECTION

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David B. Kagan
Kagan Binder, PLLC
221 Main Street No., Suite 200
Stillwater, MN 55082

Phone Number: 651-275-9804

03/21/2002 TDIAZ1 00000192 09903114
01 FC:581 40.00 OP

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $40.00
☒ Enclosed
☒ Authorized to be charged to deposit account (only if additional fees are required)

8. Deposit Account Number: 50-1775

DO NOT USE THIS SPACE

9. Statement and Signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Charges to deposit account are authorized, as indicated herein.

David B. Kagan
Printed Name of Attorney/Agent
Registration No. 33,406

David B. Kag
Signature

Feb. 22, 2002
Date

Pages: Total number of pages including COVER SHEET, attachments and documents: 11

Mail documents to be recorded with required cover sheet information to:
Commissioner for Patents, **Box Assignments**, Washington, DC 20231

(Form PTO-1595 - Modified from PTO's Rev 03/01)

ASSIGNMENT

WHEREAS, we, Devendra Kumar of 897 Altos Oaks Drive, Los Altos, California 94024, and Jeffrey D. Womack of 14309 Edenberry Drive, Lake Oswego, Oregon 97035, and Vuong P. Nguyen of 1834 Mt. Laurel Lane, Allen, Texas 75002, and Jack S. Kasahara of 130 Old Adobe Road, Los Gatos, California 95030, and Sokol Ibrani of 3692 Rockingham Drive, Pleasanton, California 94588, have invented certain new and useful improvements in THERMAL PROCESSING SYSTEM AND METHODS FOR FORMING LOW-K DIELECTRIC FILMS SUITABLE FOR INCORPORATION INTO MICROELECTRONIC DEVICES, which is identified in the United States Patent Office by Serial No. 09/903,114, filed July 11, 2001.

WHEREAS, FSI INTERNATIONAL, INC., Corporation of the State of Minnesota, and having an address of 3455 Lyman Boulevard, Chaska, Minnesota 55318-1096 is desirous of acquiring the entire right, title and interest in and to said invention, said application and in, to and under any and all Letters Patent to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said FSI INTERNATIONAL, INC., its successors and assigns, the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all rights under the International Convention, and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the above-mentioned assignee in accordance herewith.

We further authorize said assignee, it successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name, if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of the International Convention.

We do hereby covenant and agree with the said assignee, its successors and assigns, that we will not execute any writing or do any act whatsoever conflicting with these presents, and that we or our executors or administrators will, at any time upon request, without further or additional consideration, but at the expense of said assignee, its successors and assigns, execute such additional writings and do such additional acts as said assignee, its successors and assigns, may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

In witness whereof, we have hereunto signed our names on the dates set forth below.

Devendra Kumar 2/5/02

Devendra Kumar Date

Jeffrey D. Womack Date

Vuong P. Nguyen Date

Jack S. Kasahara Date

Sokol Ibrani Date

Docket No. FSI0006/US/2

ASSIGNMENT

WHEREAS, we, Devendra Kumar of 897 Altos Oaks Drive, Los Altos, California 94024, and Jeffrey D. Womack of 14309 Edenberry Drive, Lake Oswego, Oregon 97035, and Vuong P. Nguyen of 1834 Mt. Laurel Lane, Allen, Texas 75002, and Jack S. Kasahara of 130 Old Adobe Road, Los Gatos, California 95030, and Sokol Ibrani of 3692 Rockingham Drive, Pleasanton, California 94588, have invented certain new and useful improvements in THERMAL PROCESSING SYSTEM AND METHODS FOR FORMING LOW-K DIELECTRIC FILMS SUITABLE FOR INCORPORATION INTO MICROELECTRONIC DEVICES, which is identified in the United States Patent Office by Serial No. 09/903,114, filed July 11, 2001.

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In witness whereof, we have hereunto signed our names on the dates set forth below.

Devendra Kumar Date

1/27/2002
Jeffrey D. Womack Date

Vuong P. Nguyen Date

Jack S. Kasahara Date

Sokol Ibrani Date

ASSIGNMENT

WHEREAS, we, Devendra Kumar of 897 Altos Oaks Drive, Los Altos, California 94024, and Jeffrey D. Womack of 14309 Edenberry Drive, Lake Oswego, Oregon 97035, and Vuong P. Nguyen of 1834 Mt. Laurel Lane, Allen, Texas 75002, and Jack S. Kasahara of 130 Old Adobe Road, Los Gatos, California 95030, and Sokol Ibrani of 3692 Rockingham Drive, Pleasanton, California 94588, have invented certain new and useful improvements in THERMAL PROCESSING SYSTEM AND METHODS FOR FORMING LOW-K DIELECTRIC FILMS SUITABLE FOR INCORPORATION INTO MICROELECTRONIC DEVICES, which is identified in the United States Patent Office by Serial No. 09/903,114, filed July 11, 2001.

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NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said FSI INTERNATIONAL, INC., its successors and assigns, the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all rights under the International Convention, and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the above-mentioned assignee in accordance herewith.

We further authorize said assignee, it successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name, if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of the International Convention.

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In witness whereof, we have hereunto signed our names on the dates set forth below.

Devendra Kumar Date

Jeffrey D. Womack Date

1/27/02

Vuong P. Nguyen Date

Jack S. Kasahara Date

Sokol Ibrani Date

Docket No. FSI0006/US/2

ASSIGNMENT

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In witness whereof, we have hereunto signed our names on the dates set forth below.

Devendra Kumar Date

Jeffrey D. Womack Date

Vuong P. Nguyen Date

Jack S. Kasahara 1/25/02

Jack S. Kasahara Date

Sokol Ibrani Date

Docket No. FSI0006/US/2

ASSIGNMENT

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In witness whereof, we have hereunto signed our names on the dates set forth below.

Devendra Kumar Date

Jeffrey D. Womack Date

Vuong P. Nguyen Date

Jack S. Kasahara Date

1/28/02

Sokol Ibrani Date